NC7WZ38

TinyLogic UHS Dual 2-Input NAND Gate (Open Drain Output)

Description

The NC7WZ38 is a dual 2–Input NAND Gate with open drain output stage from ON Semiconductor's Ultra High Speed Series of TinyLogic. The device is fabricated with advanced CMOS technology to achieve ultra high speed with high output drive while maintaining low static power dissipation over a very broad V_{CC} operating range. The device is specified to operate over the 1.65 V to 5.5 V V_{CC} range. The inputs and output are high impedance when V_{CC} is 0 V. Inputs tolerate voltages up to 5.5 V independent of V_{CC} operating voltage. The open drain output stage will tolerate voltages up to 5.5 V independent of V_{CC} when in the high impedance state.

Features

- Space Saving US8 Surface Mount Package
- MicroPakTM Pb-Free Leadless Package
- Open Drain Output Stage for OR Tied Applications
- Ultra High Speed: t_{PD} 2.2 ns Typ. into 50 pF at 5 V V_{CC}
- High Output Sink Drive: ±24 mA at 3 V V_{CC}
- Broad V_{CC} Operating Range: 1.65 V to 5.5 V
- Matches the Performance of LCX when Operated at 3.3 V V_{CC}
- Power Down High Impedance Inputs / Output
- Overvoltage Tolerant Inputs Facilitate 5 V to 3 V Translation
- Patented Noise / EMI Reduction Circuitry Implemented
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant



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MARKING DIAGRAMS



UQFN8 1.6X1.6, 0.5P CASE 523AY





US8 CASE 846AN



U5, WZ38 = Specific Device Code

KK = 2-Digit Lot Run Traceability Code XY = 2-Digit Date Code Format Z = Assembly Plant Code

ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 5 of this data sheet.

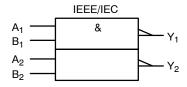


Figure 1. Logic Symbol

Connection Diagram

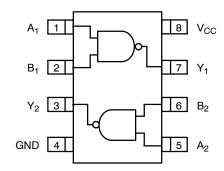
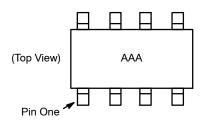


Figure 2. Connection Diagram (Top View)



AAA represents Product Code Top Mark - see ordering code

NOTE: Orientation of Top Mark determines Pin One location. Read the top product code mark left to right, Pin One is the lower left pin (see diagram).

Figure 3. Pin One Orientation Diagram

PIN DESCRIPTIONS

Pin Names	Description
A _n , B _n	Inputs
Y _n	Output

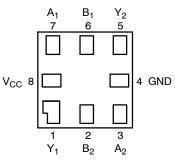


Figure 4. Pad Assignments for MicroPak (Top Thru View)

FUNCTION TABLE $(Y = \overline{AB})$

Inputs		Output
Α	В	Υ
L	L	*H
L	Н	*H
Н	L	*H
Н	Н	L

H = HIGH Logic Level

L = LOW Logic Level

*H = HIGH Impedance Output State (Open Drain)

ABSOLUTE MAXIMUM RATINGS

Symbol	Para	Parameter		Max	Unit
V _{CC}	Supply Voltage		-0.5	6.5	V
V _{IN}	DC Input Voltage		-0.5	6.5	V
V _{OUT}	DC Output Voltage		-0.5	6.5	V
I _{IK}	DC Input Diode Current	V _{IN} < -0.5 V	-	-50	mA
I _{OK}	DC Output Diode Current	V _{OUT} < -0.5 V	-	-50	mA
I _{OUT}	DC Output Current		-	±50	mA
I _{CC} / I _{GND}	DC V _{CC} / GND Current		-	±100	mA
T _{STG}	Storage Temperature	Storage Temperature		+150	°C
TJ	Junction Temperature under Bias		-	150	°C
TL	Junction Lead Temperature (Soldering, 10 Seconds)		-	260	°C
P_{D}	Power Dissipation @ +85°C		-	250	mW

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

RECOMMENDED OPERATING CONDITIONS

Symbol		Parameter	Min	Max	Unit
V _{CC}	Supply Voltage Operating		1.65	5.5	V
	Supply Voltage Data Rete	ntion	1.5	5.5	
V _{IN}	Input Voltage		0	5.5	V
V _{OUT}	Output Voltage		0	V _{CC}	V
T _A	Operating Temperature		-40	+85	°C
t _r , t _f	Input Rise and Fall Time	V _{CC} = 1.8 V ±0.15 V, 2.5 V ±0.2 V	0	20	ns/V
		V _{CC} = 3.3 V ±0.3 V	0	10	
	$V_{CC} = 5.0 \text{ V} \pm 0.5 \text{ V}$		0	5	
$\theta_{\sf JA}$	Thermal Resistance		-	250	°C/W

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

1. Unused inputs must be held HIGH or LOW. They may not float.

NC7WZ38

DC ELECTICAL CHARACTERISTICS

					Т,	գ = +25°	·C	T _A = -40	to +85°C	
Symbol	Parameter	V _{CC} (V)	Co	onditions	Min	Тур	Max	Min	Max	Unit
V _{IH}	HIGH Level Input	1.65 to 1.95			0.65 V _{CC}	_	-	0.65 V _{CC}	-	V
	Voltage	2.3 to 5.5			0.7 V _{CC}	-	-	0.7 V _{CC}	-	
V _{IL}	LOW Level Input	1.65 to 1.95			-	-	0.35 V _{CC}	_	0.35 V _{CC}	V
	Voltage	2.3 to 5.5			-	-	0.3 V _{CC}	_	0.3 V _{CC}	
I _{LKG}	HIGH Level Output Leakage	5.5	$V_{IN} = V_{IL}$ $V_{OUT} = V_{C}$	_{CC} or GND	-	-	±5	-	±10	μΑ
V _{OL}	LOW Level Output	1.65	V _{IN} = V _{IH}	I _{OL} = 100 μA	-	0.0	0.1	_	0.1	V
	Voltage	2.3			-	0.0	0.1	-	0.1	
		3.0			-	0.0	0.1	_	0.1	
		4.5			-	0.0	0.1	_	0.1	
		1.65		I _{OL} = 4 mA	-	0.08	0.24	_	0.24	
		2.3		I _{OL} = 8 mA	-	0.10	0.3	-	0.3	
		3.0		I _{OL} = 16 mA	-	0.15	0.4	_	0.4	
		3.0		I _{OL} = 24 mA	-	0.22	0.55	_	0.55	
		4.5		I _{OL} = 32 mA	-	0.22	0.55	_	0.55	
I _{IN}	Input Leakage Current	5.5	$V_{IN} = 5.5$	V, GND	-	-	±0.1	_	±1	μΑ
I _{OFF}	Power Off Leakage Current	0.0	V _{IN} or V _{OL}	_{JT} = 5.5 V	-	_	1	-	10	μΑ
I _{CC}	Quiescent Supply Current	1.65 to 5.5	V _{IN} = 5.5 \	/, GND	-	_	1	-	10	μΑ

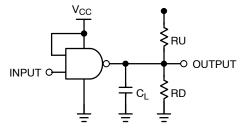
AC ELECTRICAL CHARACTERISTICS

					T _A = +25°C		T _A = -40	to +85°C	
Symbol	Parameter	V _{CC} (V)	Conditions	Min	Тур	Max	Min	Max	Unit
t _{PZL}	Propagation Delay	1.8 ±0.15	C _L = 50 pF,	-	5.2	9.2	-	9.6	ns
	(Figure 5, 7)	2.5 ±0.2	RU = 500 Ω , RD = 500 Ω ,	_	3.5	5.7	-	6.1	
		3.3 ±0.3	$V_I = 2 \times V_{CC}$	-	2.8	4.1	-	4.5	
		5.0 ±0.5		-	2.2	3.4	-	3.6	
t _{PLZ}	Propagation Delay	1.8 ±0.15	C _L = 50 pF,	-	4.6	9.2	-	9.6	ns
	(Figure 5, 7)	2.5 ±0.2	RU = 500 Ω , RD = 500 Ω ,	-	3.2	5.7	-	6.1	
		3.3 ±0.3	$V_I = 2 \times V_{CC}$	-	2.4	4.1	-	4.5	
		5.0 ±0.5		-	1.6	3.4	-	3.6	
C _{IN}	Input Capacitance	0		-	2.5	-	-	-	pF
C _{OUT}	Output Capacitance	0		-	4.2	-	-	-	pF
C _{PD}	Power Dissipation Capacitance (Figure 6)	3.3	(Note 2)	-	7	-	_	_	pF
	(i igule 0)	5.0		_	9	-	_	_	

^{2.} C_{PD} is defined as the value of the internal equivalent capacitance which is derived from dynamic operating current consumption (I_{CCD}) at no output loading and operating at 50% duty cycle. (see Figure 6) C_{PD} is related to I_{CCD} dynamic operating current by the expression: I_{CCD} = (C_{PD}) (V_{CC}) (f_{IN}) + (I_{CC}static).

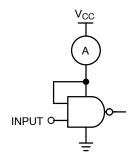
NC7WZ38

AC Loading and Waveforms



 C_L includes load and stray capacitance Input PRR = 1.0 MHz, t_W = 500 ns

Figure 5. AC Test Circuit



 $\begin{aligned} & \text{Input} = \text{AC Waveform; } t_r = t_f = 1.8 \text{ ns;} \\ & \text{PRR} = 10 \text{ MHz; } \text{Duty Cycle} = 50\%. \end{aligned}$

Figure 6. I_{CCD} Test Circuit

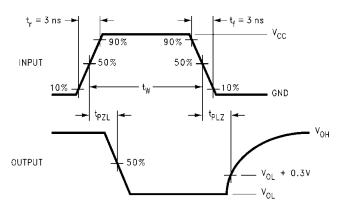


Figure 7. AC Waveforms

ORDERING INFORMATION

Order Number	Top Mark	Package	Shipping [†]
NC7WZ38K8X	WZ38	8-Lead US8, JEDEC MO-187, Variation CA 3.1 mm Wide	3000 / Tape & Reel
NC7WZ38L8X	U5	8-Lead MicroPak, 1.6 mm Wide (Pb-Free)	5000 / Tape & Reel

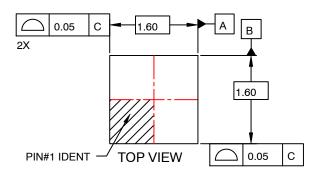
[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

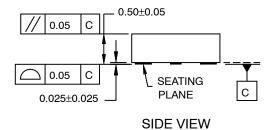
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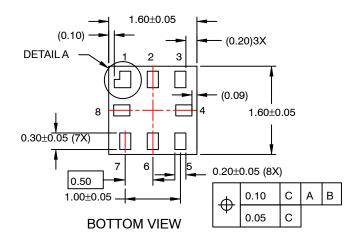
^{3.} Pb-Free package per JEDEC J-STD-020B.

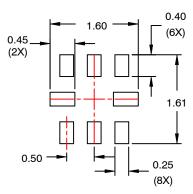
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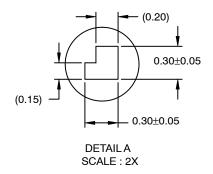




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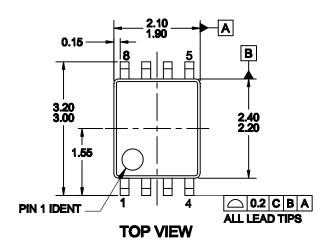


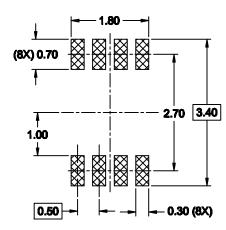
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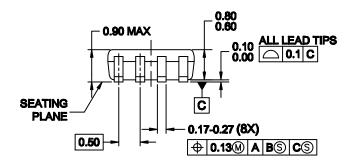
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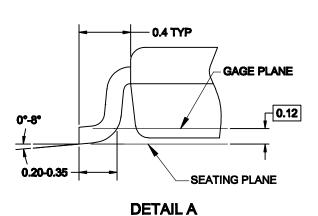
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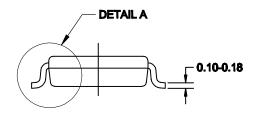


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